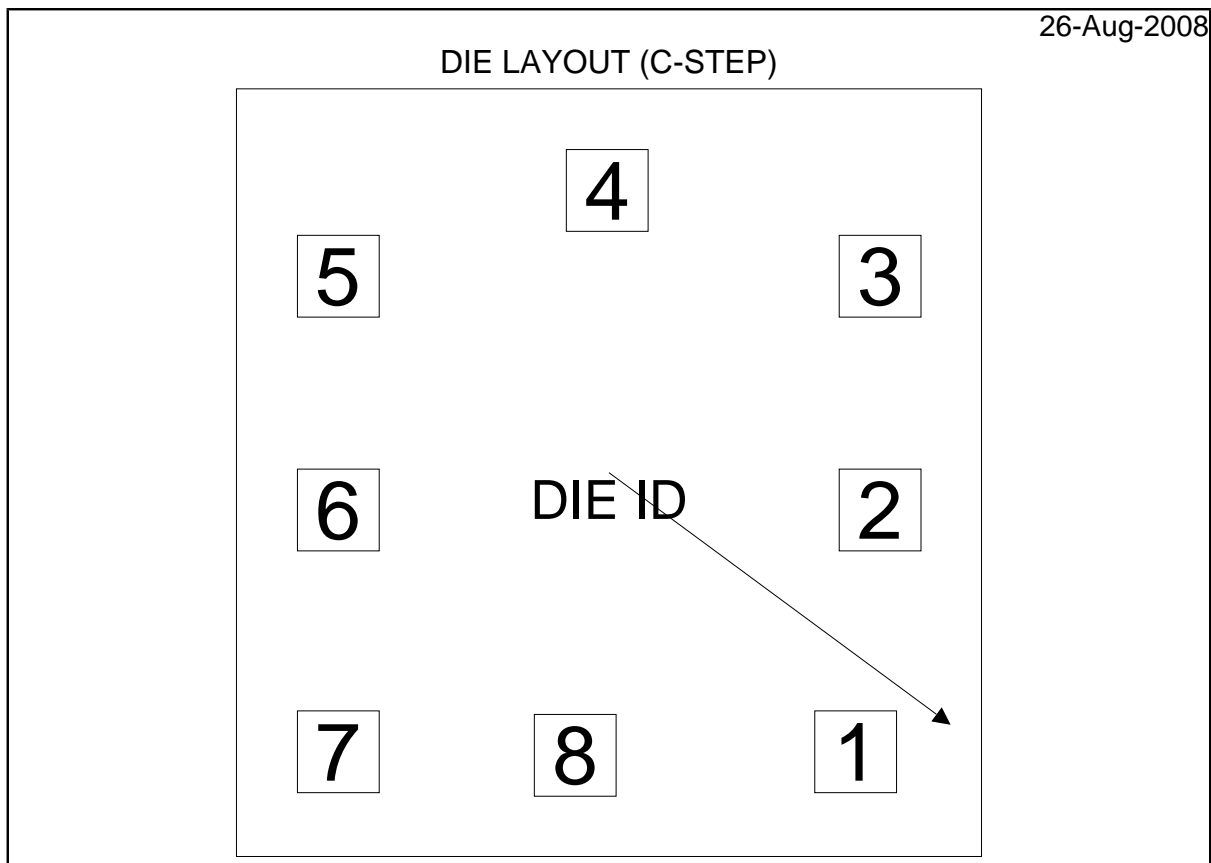


LM193 MDR MCD2930A
LOW POWER LOW OFFSET VOLTAGE DUAL COMPARATORS



DIE/WAFER CHARACTERISTICS

| Fabrication Attributes | | General Die Information | |
|-----------------------------|--|-----------------------------|-------------------|
| Physical Die Identification | LM193 | Bond Pad Opening Size (min) | 92.00µm x 92.00µm |
| Die Step | C | Bond Pad Metalization | AL 0.5%CU |
| Physical Attributes | | Passivation | VOM ONLY |
| Wafer Diameter | 150mm | Back Side Metal | BAREBACK |
| Die Size (Drawn) | 838.2µm x 863.6µm 33.0mils x 34.0mils | Back Side Connection | Floating |
| Thickness | 330µm Nominal | | |
| Min Pitch | 263µm | | |

Note: All values are rounded to the nearest micron.

Special Assembly Requirements:

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| Die Bond Pad Coordinate Locations(C-Step) | | | | | | |
|---|------------|-----------------|------|----------|---|----|
| (Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used | | | | | | |
| Signal Name | Pad Number | X/Y Coordinates | | Pad Size | | |
| | | X | Y | X | Y | |
| Output A | 1 | 277 | -314 | 92 | x | 92 |
| Input A - | 2 | 305 | -42 | 92 | x | 92 |
| Input A + | 3 | 305 | 221 | 92 | x | 92 |
| Gnd | 4 | -2 | 317 | 92 | x | 92 |
| Input B + | 5 | -304 | 221 | 92 | x | 92 |
| Input B - | 6 | -304 | -42 | 92 | x | 92 |
| Output B | 7 | -304 | -314 | 92 | x | 92 |
| V + | 8 | -38 | -318 | 92 | x | 92 |

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